

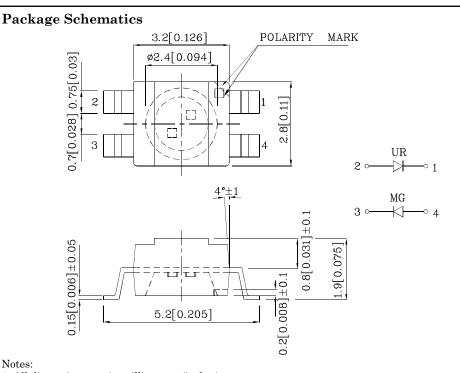
Part Number: XZURMG45S-9

3.2x2.8mm PLCC4 SMD LED

Features

- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- Standard Package: 2000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant.





1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		UR (GaAsP/ GaP)	MG (GaP)	Unit
Reverse Voltage	V_{R}	5	5	V
Forward Current	\mathbf{I}_{F}	30	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	160	140	mA
Power Dissipation	PD	75	62.5	mW
Operating Temperature	$T_{\rm A}$	-40 ~ +85		°C
Storage Temperature	Tstg	-40 ~ +85		

Operating Characteristics (T _A =25°C)		UR (GaAsP/ GaP)	MG (GaP)	Unit
Forward Voltage (Typ.) (I _F =20mA)	$V_{\rm F}$	2	2.2	v
Forward Voltage (Max.) (I _F =20mA)	$V_{\rm F}$	2.5	2.5	v
Reverse Current (Max.) (V _R =5V)	I_R	10	10	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λP	627 627*	565 565*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =20mA)	λD	$625 \\ 617*$	568 568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle \lambda$	45	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	15	pF
$\begin{array}{c} \mbox{Luminous In} \\ \mbox{Lens-color} & \mbox{CIE127-20} \\ \mbox{(I_F=20mA)} \end{array}$	007*	Wavelen CIE127-20 λP nm	007* Ang	gle
min.	typ.			

				min.	typ.		
XZURMG45S-9	Red	GaAsP/GaP	Water Clear -	12 8*	29 15*	627*	1009
	Green	GaP		12 12*	29 30*	565*	- 120°

Emitting

Material

*Intensity intensity value and wavelength are in accordance with CIE127-2007 standards.

Emitting

Color

Oct 30,2012

Part

Number

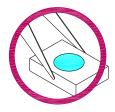
XDSB5417 V2-X Layout: Maggie L.



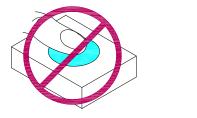
Handling Precautions

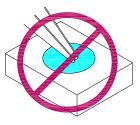
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

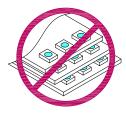


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

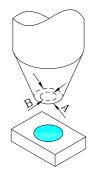




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.

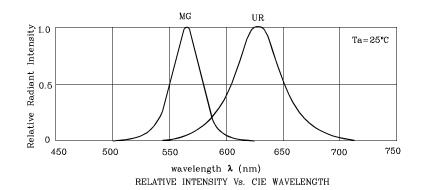


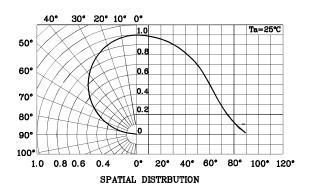
4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.



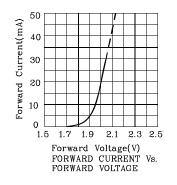


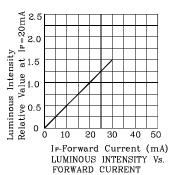


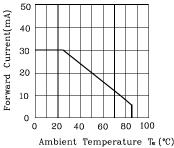
Intensity

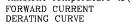
Luminous

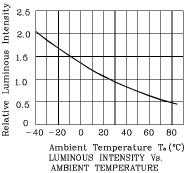
♦ UR



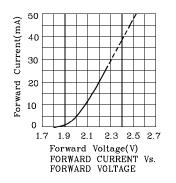


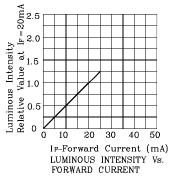


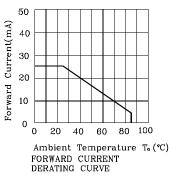


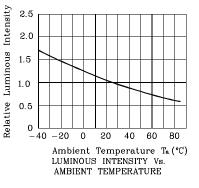


♦ MG











300 (°C)

250

200

150

100

50

Notes

Temperature

LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

4°C/s

80~120

100

high temperatures conditions

Tim

2. Recommended reflow temperature: 145°C-260°C

3. Do not put stress to the epoxy resin during

150

Maximum soldering temperature should not exceed 260°C

200

150~180°C

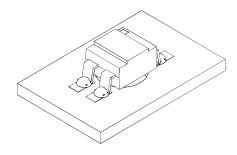
4℃/s max

10 8

C/s

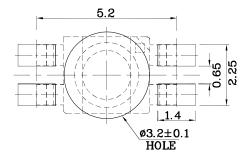
250

300 (sec) The device has a single mounting surface. The device must be mounted according to the specifications.

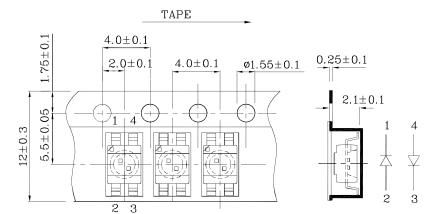


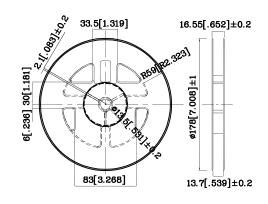
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

Reel Dimension



Tape Specification (Units : mm)





Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS

